Title (en)

Method of producing a dielectric strip line

Title (de)

Verfahren zur Herstellung eines dielektrischen Streifenleiters

Title (fr)

Procédé d'obtenir une diélectrique ligne à bande

Publication

EP 1065745 A3 20070328 (EN)

Application

EP 00112723 A 20000615

Priority

JP 17879099 A 19990624

Abstract (en)

[origin: EP1065745A2] The present invention provides a method of producing a dielectric line which is capable of producing a dielectric line at low cost with causing neither cracks nor chips in processing and high precision of each dimension of a dielectric strip. The method of producing a dielectric line having a dielectric strip provided between a plurality of substantially parallel conductive planes includes the step of forming a resist material on a green sheet containing at least an inorganic powder and an organic binder; the step of removing a desired amount of the green sheet corresponding to an aperture of the resist material used as a mask; the step of removing the resist material; and the step of burning the green sheet.

IPC 8 full level

H01P 3/16 (2006.01); **H01P 11/00** (2006.01)

CPC (source: EP)

H01P 3/165 (2013.01); **H01P 11/006** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

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DOCDB simple family (publication)

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